

In the claims:

1. (currently amended) An interconnection device comprising:

first and second outer layers, each including substrate material;

at least one inner layer disposed between said first and second outer layers, said inner layer including at least one conductive signal trace disposed on a rigid substrate material proximate to an edge of the interconnection device and being accessible for direct electrical connection with a corresponding exposed signal trace, wherein at least one conductive protrusion is formed on said conductive inner layer trace, and wherein said protrusion is resilient; and

shielding disposed around the at least one signal trace, including a first shielding wall on a layer below the trace, a second shielding wall on a layer above the trace, and third and fourth shielding walls on either side of the trace, the first, second, third and fourth shielding walls being connected such that uninterrupted shielding is provided for 360° around the trace.

2. (previously presented) The interconnection device of claim1 wherein said conductive inner layer trace extends outward from the edge of the interconnection device.

3. (original) The interconnection device of claim 1 wherein at least a portion of said first outer layer is removed to provide access to said conductive inner layer trace.

4. (cancelled )

5. (previously presented) The interconnection device of claim 1 wherein said protrusion is malleable.

6. (cancelled)

7. (cancelled)

8. (cancelled)

9. (cancelled)

10. (cancelled)

11. (cancelled)

12. (currently amended) An interconnection device comprising:

a printed circuit board having first and second outer layers, each including substrate material;

at least one inner layer disposed between said first and second outer layers, said inner layer including at least one conductive signal trace disposed on substrate material proximate to an edge of the interconnection device and being accessible for direct electrical connection with a corresponding signal trace, wherein at least one conductive protrusion is formed on said at least one conductive signal trace, and wherein said protrusion is resilient, and wherein said inner layer substrate material is a ceramic; and

shielding disposed around the at least one signal trace, including a first shielding wall on a layer below the trace, a second shielding wall on a layer above the trace, and third and fourth shielding walls on either side of the trace, the first, second, third and

fourth shielding walls being connected such that uninterrupted shielding is provided for 360° around the trace.

13. (original) The interconnection device of claim 1 wherein said inner layer substrate material is organic.

14. (cancelled)

15. (cancelled)

16. (cancelled)

17. (cancelled)

18. (cancelled)

19. (cancelled)

20. (cancelled)

21. (cancelled)

22. (cancelled)

23. (cancelled)

24. (cancelled)

25. (cancelled)

26. (cancelled)

27. (cancelled)

28. (cancelled)

29. (previously presented) The interconnection device of claim 12 wherein said conductive inner layer trace extends outward from the edge of the interconnection device.

30. (previously presented) The interconnection device of claim 12 wherein at least a portion of said first outer layer is removed to provide access to said conductive inner layer trace.

31. (previously presented) The interconnection device of claim 12 wherein at least one conductive protrusion is formed on said conductive inner layer trace.

32. (previously presented) The interconnection device of claim 31 wherein said protrusion is malleable.

33. (cancelled)

34. (new) An interconnection device comprising:

first and second outer layers, each including substrate material;

at least one inner layer disposed between said first and second outer layers, said inner layer including at least one conductive signal trace disposed on a rigid substrate material proximate to an edge of the interconnection device and being accessible for direct electrical connection with a corresponding exposed signal trace, wherein at least one conductive protrusion is formed on said conductive inner layer trace, and wherein said protrusion is malleable; and

shielding disposed around the at least one signal trace, including a first shielding wall on a layer below the trace, a second shielding wall on a layer above the trace, and third and fourth shielding walls on either side of the trace, the first, second, third and fourth shielding walls being connected such that uninterrupted shielding is provided for 360° around the trace.

35. (new) An interconnection device comprising:

a printed circuit board having first and second outer layers, each including substrate material;

at least one inner layer disposed between said first and second outer layers, said inner layer including at least one conductive signal trace disposed on substrate material proximate to an edge of the interconnection device and being accessible for direct electrical connection with a corresponding signal trace, wherein at least one conductive protrusion is formed on said at least one conductive signal trace, and wherein said protrusion is malleable, and wherein said inner layer substrate material is a ceramic; and

shielding disposed around the at least one signal trace, including a first shielding wall on a layer below the trace, a second shielding wall on a layer above the trace, and third and fourth shielding walls on either side of the trace, the first, second, third and fourth shielding walls being connected such that uninterrupted shielding is provided for 360° around the trace.